



HYCLEANSE® 300FG

Entec Polymers - High Density Polyethylene

Tuesday, November 5, 2019

General Information

Product Description

The least cost prohibitive purging compound in the plastics industry.

HYCLEANSE-300FG Purge contains several proprietary additives plus short-strand fiberglass that are essential in the cleansing process of high temperatures as well as lower melting polyolefins. HyCleanse-300FG Purge was also created to be the least cost prohibitive glass filled cleansing compound in the market. HyCleanse 300FG can be used directly without any mixing necessary to clean most plastic equipment during color and resin changes. The unique additives and resin system in HyCleanse-300FG Purge, makes it possible to purge color resins like Polyolefins, A.B.S., Styrenics as well as PC, Nylon, PEEK and Ultem in less time and with less smoke than most cleansing compounds on the market.

Features and Benefits:

HyCleanse-300FG Purge is easy to use and no process changes are needed. Use at the normal resin processing temperature and RPM speed. No mixing is required. Also HyCleanse-300FG Purge is not just a Mechanical purge.

Applications: Injection Molding - Pipe/Profile - Compounding

Types of Resins: PE, PP, PS, PA, POM, ABS, PEEK, PC/ABS, Ultem

General

Material Status	• Commercial: Active
Availability	• North America
Filler / Reinforcement	• Glass Fiber
Additive	• Proprietary
Uses	• Purging Compound
Agency Ratings	• FDA Unspecified Rating

ASTM & ISO Properties ¹

Physical	Nominal Value	Unit
Density	0.955	g/cm ³
Melt Mass-Flow Rate (190°C/2.16 kg)	0.30 to 0.50	g/10 min
Additional Information	Nominal Value	Unit
Temperature Range	350 to 600	°F

Notes

¹ Typical properties: these are not to be construed as specifications.